

**AMENDMENTS TO THE DRAWINGS**

In response to the drawing objection, a replacement sheet of Fig. 3 is submitted herewith to show the feature of “a light-emitting diode comprising a flip-chip-type gallium nitride compound semiconductor light-emitting device”.

Please cancel current Figure 3 and replace with the attached replacement drawing sheet.

Attachment: One (1) Replacement Sheet (Fig. 3)

**REMARKS**

Upon entry of the present Amendment, claims 1, 4-9 and 12 will be all the claims pending in the application. Claims 1 and 9 have been amended. Claims 2-3, 10-11 and 13 were canceled without prejudice.

Claims 1 and 9 have been amended to more clearly point out the claimed subject matter. Claims 1 and 9 have been amended to recite wherein the bonding pad layer is provided atop a portion less than the entirety of the ohmic electrode layer, and that the adhesion layer has the same dimension as the bonding pad layer. Support for the amendment to claim 1 can be found in the specification, for example, at page 9, last paragraph bridging page 10, and Figure 2.

No new matter has been added. Entry of the Amendment is respectfully requested. Further, entry of the amendment at this stage of prosecution is respectfully requested as placing the case in condition for allowance.

**I. Response to Specification and Drawing Objection**

The Examiner objected to the Applicants' Amendment filed on February 29, 2008 as introducing new matter into the specification. Specifically, the Examiner considered that the added material with regard to Figure 3 is not supported by the original disclosure, and that the added Figure 3 introduces "too many" features not supported by the original disclosure.

Without acquiescence in the merits of the above objection, and to advance prosecution, Applicants submit herewith a simplified replacement drawing Fig. 3 to show the feature of "a light-emitting diode comprising a flip-chip-type gallium nitride compound semiconductor light-emitting device". No new matter has been added.

Withdrawal of the objection to the specification and acceptance of the replacement sheet of Fig. 3 are respectfully requested.

## **II. Response to Claim Rejection under 35 U.S.C. § 103 Over Kamimura**

Claims 1, 4-9 and 12 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Kamimura et al. (JP 2002368271 A; "Kamimura").

Applicants respectfully traverse this rejection.

Independent claims 1 and 9 presently recite that the bonding pad layer is provided atop a portion less than the entirety of the ohmic electrode layer, and that the adhesion layer has the same dimension as the bonding pad layer.

In contrast, Kamimura discloses that preferably the whole front face of p lateral electrode is covered and p-lateral electrode film is formed thereon. Paragraph [0009]. Further, Kamimura discloses that it is desirable to make the configuration of n-lateral electrode film the same as that of the configuration of p-lateral electrode film. Paragraph [0015]. Figure 1 of Kamimura clearly shows that the whole front face of both the n-lateral electrode and the p-electrode are covered by electrode films, respectively.

The amendment to claims 1 and 9 clearly distinguishes over the structure disclosed by Kamimura. Moreover, there is no apparent reason which would lead one of ordinary skill to form bonding pad layer (upper layer) 20b of Kamimura on anything less than the entirety of the underlying ohmic electrode layer. Accordingly, it is respectfully submitted that the present claims are patentable over Kamimura, and withdrawal of the foregoing rejection under 35 U.S.C. § 103 is requested.

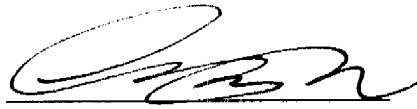
## **III. Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the

Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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**23373**

CUSTOMER NUMBER

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